

Please replace the paragraph at Page 3, Column 6, lines 31-41 with the following amended paragraph:

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In case the aforementioned individual portions are formed by the pressing, burrs 11 are left on the back of the cut portions. Since the leadframe 1 of the present embodiment is made such that the die pad 3 has a smaller area than that of the semiconductor chip 2 to be mounted thereon, the burrs 11, if any, on the face of the die pad 3 for mounting the semiconductor chip 2 will be unable to mount the chip 2. When the die pad 3 is to be pressed, therefore, it is pressed with its chip mounting [Face] face being directed upward so that the burrs 11 may be left on the back opposed to the chip mounting face. f.

Please replace the paragraph at Page 4, Column 8, lines 46-50 with the following amended paragraph:

Q3
As shown in FIG. 15, moreover, slightly wider small pads (or adhesion-applied portions) 20 than the suspension leads 4 may be formed around the die pad 5 so that the adhesive [1S] 15 may be applied to the individual principal faces of the die pad 3 and the small pads 20. f.

IN THE CLAIMS:

(NC) Please cancel Claims 37-49, without prejudice or disclaimer.

Please add new Claims 15-27, as follows.

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15.(New) A semiconductor device comprising:

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(a) a semiconductor chip having a plurality of semiconductor elements and bonding pads formed on a main surface thereof;

(b) a lead frame having:

a chip mounting portion having one surface for mounting said semiconductor chip; and

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a plurality of leads each having an inner lead portion and an outer lead portion continuously formed with said inner lead portion and being arranged at a periphery of said chip mounting portion, said inner lead portions of said plurality of leads being electrically connected with said bonding pads of said semiconductor chip; and

(c) a resin member sealing said semiconductor chip, said chip mounting portion and said inner lead portions of said plurality of leads,

wherein a size of said chip mounting portion is smaller than that of said semiconductor chip, and

wherein said one surface of said chip mounting portion is a surface on which burrs are not formed, during formation of said chip mounting portion.

16.(New) A semiconductor device according to Claim 15, wherein said burrs are formed when said lead frame is made by pressing.

17.(New) A method of manufacturing a semiconductor device according to Claim 15, wherein said chip mounting portion has a substantially circular form in a plane view.

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18.(New) A method of manufacturing a semiconductor device according to Claim 16, wherein said chip mounting portion has a substantially cross form in a plane view.

19.(New) A semiconductor device according to Claim 15, wherein said inner lead portions of said plurality of leads are electrically connected with said bonding pads of said semiconductor chip by a plurality of bonding wires.

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20.(New) A semiconductor device according to Claim 19, wherein parts of said inner lead portions of said plurality of leads, to which said plurality of bonding wires are connected, are plated.

21.(New) A semiconductor device comprising:

(a) a semiconductor chip having a plurality of semiconductor elements and bonding pads formed on a main surface thereof;

(b) a lead frame having:

a chip mounting portion for mounting said semiconductor chip; and

a plurality of leads each having an inner lead portion and an outer lead portion continuously formed with said inner lead portion and being arranged at a periphery of said chip mounting portion.

(c) a plurality of bonding wires electrically connecting said inner lead portions of said plurality of leads with said bonding pads of said semiconductor chip respectively, each of said inner lead portions of said plurality of leads having one surface to which a corresponding bonding wire among said plurality of bonding wires is connected; and

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(d) a resin member sealing said semiconductor chip, said plurality of bonding wires, said chip mounting portion and said inner lead portions of said plurality of leads.

wherein said one surface of said inner lead portion of each of said plurality of leads is a surface on which burrs are formed, said burrs being resultant from formation of said plurality of leads.

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22.(New) A semiconductor device according to Claim 21, wherein a size of said chip mounting portion is smaller than that of said semiconductor chip.

23.(New) A semiconductor device according to Claim 21, wherein said burrs are formed when said lead frame is made by pressing.

24.(New) A semiconductor device according to Claim 22, wherein said chip mounting portion has a substantially circular form in a plane view.

25.(New) A semiconductor device according to Claim 22, wherein said chip mounting portion has a substantially cross form in a plane view.

26.(New) A semiconductor device comprising:

(a) a semiconductor chip having a plurality of semiconductor elements and bonding pads formed on a main surface thereof;

(b) a lead frame having:

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wherein a size of said chip mounting portion is smaller than that of said
semiconductor chip,

wherein said first surface of said chip mounting portion is a surface on which
burrs are not formed, and

wherein said second surface of said inner lead portion of each of said plurality
of leads is a surface on which said burrs are formed, said burrs resultant from
formation of said chip mounting portion and said plurality of leads.

27.(New) A method of manufacturing a semiconductor device, comprising the
steps of: